

Sound Processor with Built-in 3-band Equalizer

BD37524FS

General Description

BD37524FS is a sound processor with built-in 3-band equalizer for car audio. Other features are stereo 5ch input selector, input-gain control, main volume, loudness, 5ch fader volume, LPF for subwoofer, level meter. It is equipped with an "Advanced switch circuit", which is an original ROHM technology that reduces various switching noise (ex. No-signal, low frequency likes 20Hz & large signal inputs). The "Advanced switch" makes control of microcomputer easier and can be used for designing high quality car audio systems.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, treble, and loudness by using advanced switch circuit
- Built-in differential input selector and single-ended input selectors
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces switching noise for volume of a portable audio input.
- Lesser number of external components due to built-in 3-band equalizer filter, LPF for subwoofer, loudness filter. This makes,it possible to control the Q, Gv, fo of 3-band equalizer, fc of LPF, fo, and Gv of loudness through I²C BUS.
- A gain adjustment quantity of ±20dB with 1 dB step gain adjustment is possible for bass, middle, and treble.
- Built-in subwoofer output terminals.
- Energy-saving design resulting in low current consumption is achieved by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input pins and output pins are organized and separately laid out to keep the signal flow in one direction which consequently, simplify pattern layout of the set board and decrease the board dimensions.
- It is possible to be controlled by a 3.3V / 5V I²C BUS

Key Specifications

Power Supply Voltage Range: 7.0V to 9.5VCircuit Current (No Signal): 38mA(Typ)

■ Total Harmonic Distortion1

(FRONT,REAR): 0.001%(Typ)

■ Total Harmonic Distortion2

(SUBWOOFER): 0.002%(Typ)

Maximum Input Voltage: 2.3Vrms(Typ)

Cross-talk Between Selectors: -100dB(Typ)

Volume Control Range: +15dB to -79dB

Output Noise Voltage1

(FRONT,REAR): $3.8\mu Vrms(Typ)$

■ Output Noise Voltage2

(SUBWOOFER): 4.8μVrms(Typ)
Residual Output Noise Voltage: 1.8μVrms(Typ)
Operating Temperature Range: -40°C to +85°C

Package

 $W(Typ) \times D(Typ) \times H(Max)$

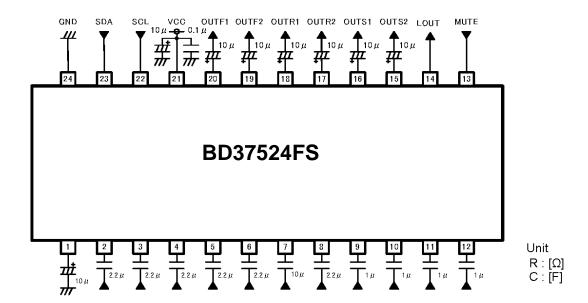


SSOP-A24 10.00mm x 7.80mm x 2.10mm

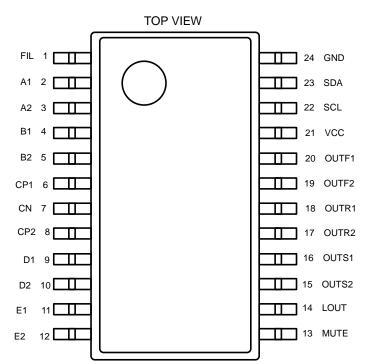
Applications

It is optimal for car audio systems. It is also suitable for other audio equipment such as mini Compo, micro Compo, TV etc

Typical Application Circuit



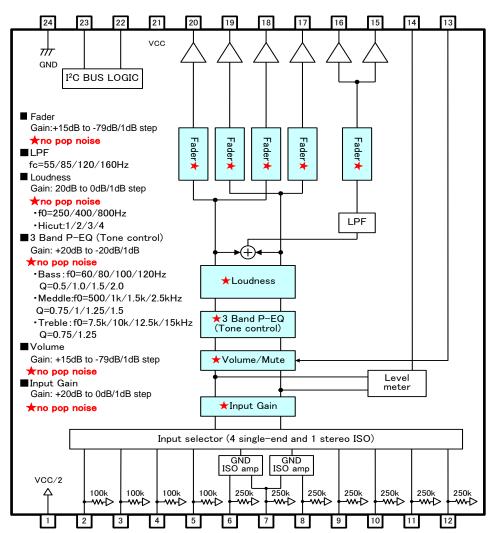
Pin Configuration



Pin Descriptions

Descript	10115				
Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	FIL	VCC/2 terminal	13	MUTE	External compulsory mute terminal
2	A1	A input terminal of 1ch	14	LOUT	Output terminal for Level meter
3	A2	A input terminal of 2ch	15	OUTS2	Subwoofer output terminal of 2ch
4	B1	B input terminal of 1ch	16	OUTS1	Subwoofer output terminal of 1ch
5	B2	B input terminal of 2ch	17	OUTR2	Rear output terminal of 2ch
6	CP1	C positive input terminal of 1ch	18	OUTR1	Rear output terminal of 1ch
7	CN	C negative input terminal	19	OUTF2	Front output terminal of 2ch
8	CP2	C positive input terminal of 2ch	20	OUTF1	Front output terminal of 1ch
9	D1	D input terminal of 1ch	21	VCC	Power supply terminal
10	D2	D input terminal of 2ch	22	SCL	I ² C Communication clock terminal
11	E1	E input terminal of 1ch	23	SDA	I ² C Communication data terminal
12	E2	E input terminal of 2ch	24	GND	GND terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power supply Voltage	Vcc	10.0	V
Input voltage	VIN	V _{CC} +0.3 to GND-0.3	V
Power Dissipation	Pd	1 (Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on standard board (70 x 70 x 1.6(mm³)), derate by 8mW/°C for Ta above25°C.

Thermal resistance θja = 125(°C/W)

Material: A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	Vcc	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

Electrical Characteristics

(Unless otherwise noted, Ta=25°C, V_{CC} =8.5V, f=1kHz, V_{IN} =1Vrms, Rg=600 Ω , RL=10k Ω , A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, Fader 0dB)

	Of 1, volume odb, fone control odb,		<u>,</u> .	Limit			
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current (No Signal)	lα	-	38	48	mA	No signal
	Voltage Gain	G _V	-1.5	0	+1.5	dB	G _V =20log(V _{OUT} /V _{IN})
	Channel Balance	СВ	-1.5	0	+1.5	dB	$CB = G_{V1} - G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	1	0.001	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
RAL	Output Noise Voltage 1 (FRONT,REAR) *	V _{NO1}	-	3.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GENERAL	Output Noise Voltage 2 (SUBWOOFER) *	V _{NO2}	-	4.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
	Residual Output Noise Voltage *	V _{NOR}	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Crosstalk Between Channels *	СТС	-	-100	-90	dB	$ Rg = 0\Omega \\ CTC=20log(V_{OUT}/V_{IN}) \\ BW = IHF-A $
	Ripple Rejection	RR	-	-70	-40	dB	f=1KHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{OUT})
	Input Impedance(A, B)	R _{IN_S}	70	100	130	kΩ	
~	Input Impedance (C,D,E)	R _{IN_D}	175	250	325	kΩ	
стоғ	Maximum Input Voltage	V _{IM}	2.1	2.3	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
INPUT SELECTOR	Crosstalk Between Selectors *	CTS	1	-100	-90	dB	$Rg = 0\Omega$ $CTS=20log(V_{OUT}/V_{IN})$ BW = IHF-A
INP	Common Mode Rejection Ratio *	CMRR	50	65	1	dB	CP1 and CN input CP2 and CN input CMRR=20log(V _{IN} /V _{OUT}) BW = IHF-A
SAIN	Minimum Input Gain	G _{IN_МIN}	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT GAIN	Maximum Input Gain	GIN_MAX	18	20	22	dB	Input gain 20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
	Gain Set Error	G _{IN_ERR}	-2	0	+2	dB	GAIN=+20dB to +1dB

Electrical Characteristics - continued

	al Characteristics - continue	<u>u</u>		Limit			
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
MUTE	Mute Attenuation *	G _{мите}	-	-105	-85	dB	Mute ON GMUTE=20log(VOUT/VIN) BW = IHF-A
	Maximum Gain	G _{V_MAX}	13	15	17	dB	Volume = 15dB V _{IN} =100mVrms Gv=20log(Vout/Vin)
VOLUME	Maximum Attenuation *	G _{V_MIN}	-	-100	-85	dB	Volume = -∞dB Gv=20log(Vout/Vin) BW = IHF-A
>	Attenuation Set Error 1	G _{V_ERR1}	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	G _{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G _{V_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
SS	Maximum Boost Gain	G _{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms G _B =20log (V _{OUT} /V _{IN}) Gain=-20dB f=100Hz
BASS	Maximum Cut Gain	G в_сит	-22	-20	-18	dB	V _{IN} =2Vrms G _B =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{B_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=100Hz
щ	Maximum Boost Gain	G _{M_BST}	18	20	22	dB	gain=+20dB f=1KHz V _{IN} =100mVrms G _M =20log (V _{OUT} /V _{IN})
MIDDLE	Maximum Cut Gain	G м_сит	-22	-20	-18	dB	Gain=-20dB f=1KHz V _{IN} =2Vrms G _M =20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{M_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=1KHz
щ	Maximum Boost Gain	G _{T_BST}	18	20	22	dB	Gain=+20dB f=10kHz V _{IN} =100mVrms G _T =20log (V _{OUT} /V _{IN})
TREBLE	Maximum Cut Gain	G т_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms GT=20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{T_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=10kHz
	Maximum Boost Gain	G _{F_BST}	13	15	17	dB	Fader=15dB V _{IN} =100mVrms G _F =20log(V _{OUT} /V _{IN})
SUBWOOFER	Maximum Attenuation *	G _{F_MIN}	-	-100	-90	dB	Fader = $-\infty$ dB $G_F=20log(V_{OUT}/V_{IN})$ BW = IHF-A
BW	Gain Set Error	G _{F_ERR}	-2	0	+2	dB	Gain=+15dB to +1dB
	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=-1dB to -15dB
.R	Attenuation Set Error 2	G _{F_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
FADER /	Attenuation Set Error 3	G _{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
T.	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	Vом	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz
LOUDNESS	Maximum Gain	G _{L_MAX}	17	20	23	dB	Gain 20dB V _{IN} =100mVrms G _L =20log(V _{OUT} /V _{IN})
ГОП	Gain Set Error	G _{L_ERR}	-2	0	+2	dB	GAIN=+20dB to +1dB
vel ter	Maximum Output Voltage	V _{L_MAX}	2.8	3.1	3.5	V	
Level	Output Offset Voltage	V _{L_OFF}	-	0	100	mV	
VD occ	90A(Average value detection, effective value		. Matauahit	- Cammuni			

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

Typical Performance Curves

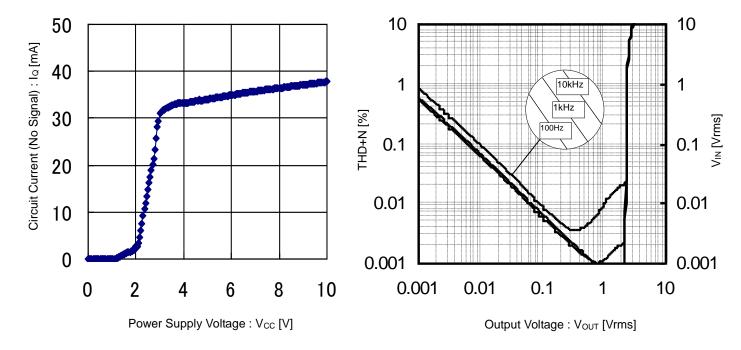


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

Figure 2. THD+N vs Output Voltage

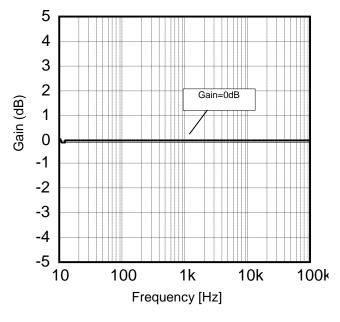


Figure 3. Gain vs Frequency

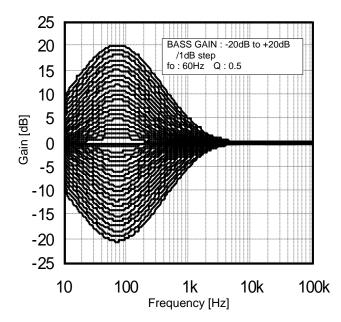


Figure 4. Bass Gain vs Frequency

Typical Performance Curves - continued

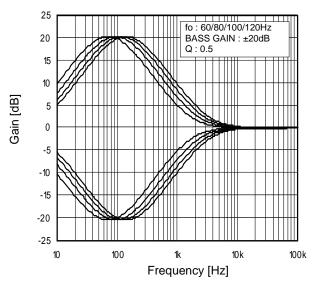


Figure 5. Bass fo vs Frequency

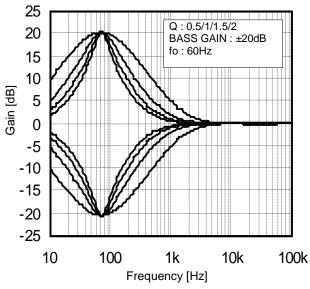


Figure 6. Bass Q vs Frequency

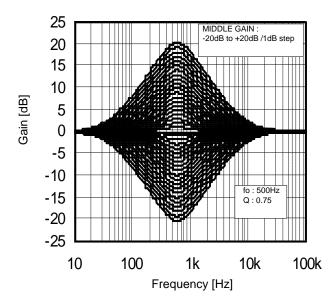


Figure 7. Middle Gain vs Frequency

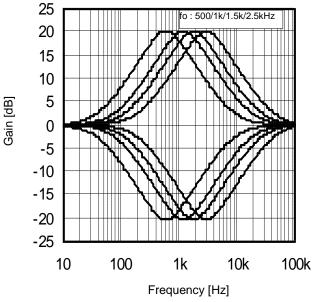


Figure 8. Middle fo vs Frequency

Typical Performance Curves - continued

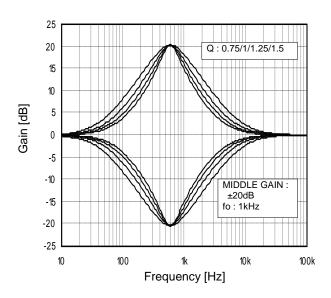


Figure 9. Middle Q vs Frequency

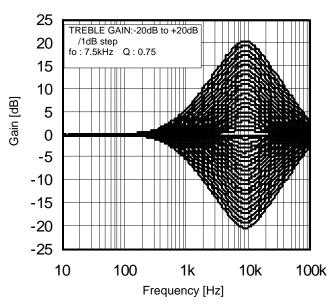


Figure 10. Treble Gain vs Frequency

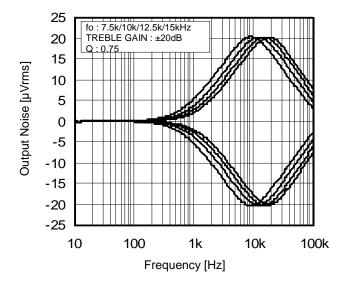


Figure 11. Treble fo vs Frequency

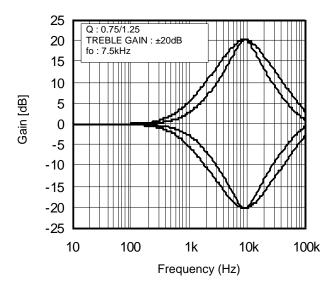


Figure 12. Treble Q vs Frequency

Typical Performance Curves – continued

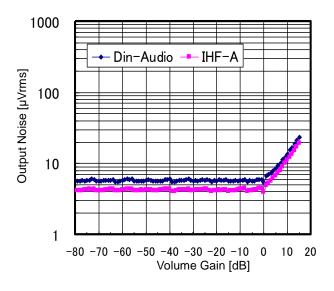


Figure 13. Output Noise vs Volume Gain

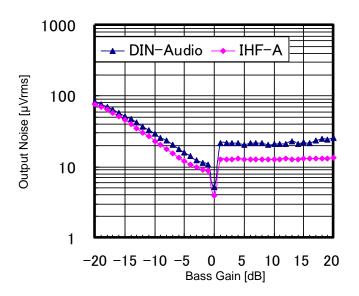


Figure 14. Output Noise vs Bass Gain

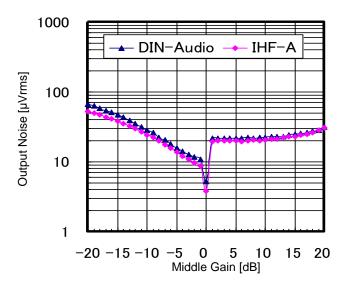


Figure 15. Output Noise vs Middle Gain

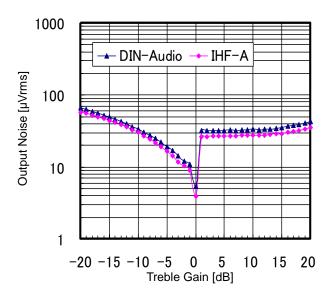


Figure 16. Output Noise vs Treble Gain

Typical Performance Curves - continued

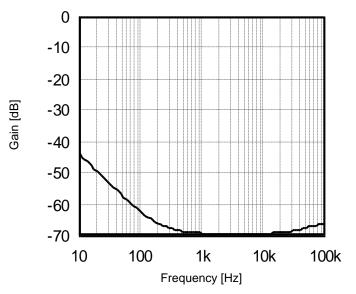


Figure 17. CMRR vs Frequency

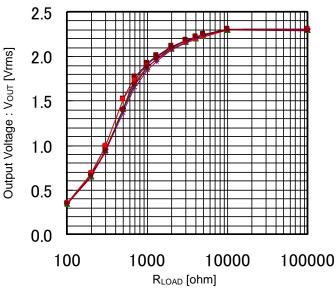


Figure 18. Output Voltage vs RLOAD

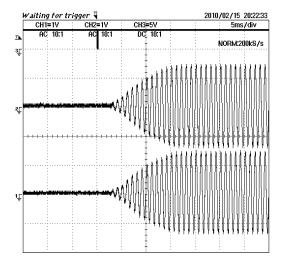


Figure 19. Advanced Switch 1

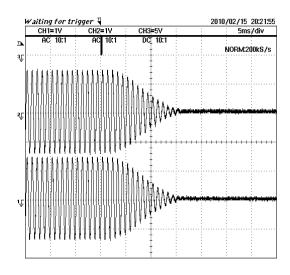


Figure 20. Advanced Switch 2

Typical Performance Curves - continued

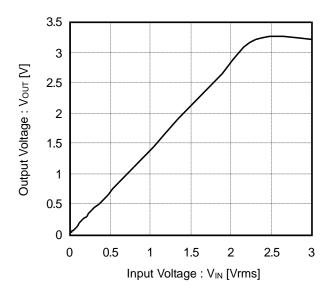


Figure 21. Output Voltage vs Level Meter VIN

Timing Chart

Control Signal Specification

(1) <u>Electrical Specifications and Timing for Bus Lines and I/O Stages</u>

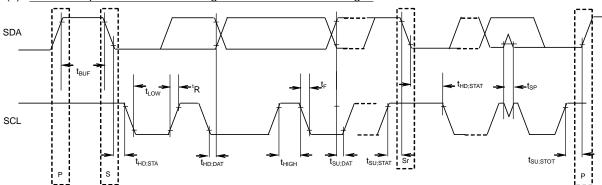


Figure 22. Definition of Timing on the I²C-bus

Table 1 Characteristics of the SDA and SCL bus lines for I^2C -bus devices (Unless specified otherwise, Ta=25°C, V_{CC} =8.5V)

	Parameter	Symbol	Fast-mode	e I ² C-bus	Unit
	T drainoto.	Cymbol	Min	Max	0
1	SCL clock frequency	f _{SCL}	0	400	kHz
2	Bus free time between a STOP and START condition	t _{BUF}	1.3	ı	μS
3	Hold time (repeated) START condition. After this period, the first clock pulse is generated	thd;sta	0.6	-	μS
4	LOW period of the SCL clock	t _{LOW}	1.3	-	μS
5	HIGH period of the SCL clock	thigh	0.6	-	μS
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS
7	Data hold time:	t _{HD;DAT}	0.06 ^(Note)	ı	μS
8	Data set-up time	t _{SU;DAT}	120	-	ns
9	Set-up time for STOP condition	tsu;sто	0.6	-	μS

All values are referred to VIH min and VIL max Levels (see Table 2).

(Note) The device must internally provide a hold time of at least 300 ns for the SDA signal (refer to the VIH min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

For $7(t_{\text{HD;DAT}})$ and $8(t_{\text{SU;DAT}}),$ make the setup in which the margin is fully in .

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Symbol	Fast-mode	Unit	
	r didilioto.	Cymbol	Min	Max	Omi
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	ViH	2.3	5	٧
12	Pulse width of spikes which must be suppressed by the input filter.	t _{SP}	0	50	ns
13	LOW level output voltage: at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	l ₁	-10	+10	μA

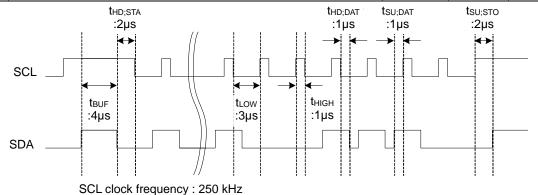


Figure 23. A Command Timing Example in the I²C Data Transmission

(2) <u>I²C BUS FORMAT</u>

		MSB LS	SB	MSB	LSB		MSB	LSB				
Ī	S	Slave Address	Α	A Select Address		Α	D	ata	Α	Р		
	1bit	8bit	1bit	1bit 8bit		1bit	;	8bit	1bit	1bit		
		S	= S	= Start condition (Recognition of start bit)								
		Slave Addres	ss = R	= Recognition of slave address. The first 7 bits corresponds to slave address								
			TI	The least significant bit is "L" corresponds to write mode.								
		Α	= A	= ACKNOWLEDGE bit (Recognition of acknowledgement)								
		Select Addre	ss = S	= Select address for volume, bass and treble.								
		Data	= D	= Data on every volume and tone.								
		Р	= S	= Stop condition (Recognition of stop bit)								

(3) I²C BUS Interface Protocol

(a) Basic form

S	Slave Addre	SS	Α	Select A	ddress	Α	Data	Α	Р
	MSB	LSB	Ν	MSB	LSB	M	SB LS	SB	

(b) Automatic increment (Select Address increases (+1) according to the number of data.

S	Slave Addres	ss	Α	Select Address	Α	Data1	Α	Dat	a2	Α		DataN	Α	Р	l
	MSB L	_SB	MS	B LSB	MS	B LSB		MSB	LSB	}	1	MSB LS	BB		

(Example) ①Data1 shall be set as data of address specified by Select Address.

- ②Data2 shall be set as data of address specified by Select Address +1.
- ③DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration unavailable for transmission (In this case, only Select Address1 is set.

S	Slave Add	dress A	A Select	Address1	Α [Data	Α	Select	Address 2	Α	Data	Α	Р
	MSB	LSB	MSB	LSB	MSE	3 LS	В	MSB	LSB	MS	SB LS	SB	
	(Note)	If any da	ata is transi	mitted as Se	elect A	ddres	s 2 r	next to da	ıta, it is reco	gnize	ed		
		as dat	a. not as S	elect Addres	ss 2.								

(4) Slave address

MSB							LSB	
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Items	Select Address	MSB			Di	ata			LSB			
nems	(hex)	D7	D6	D5	D4	D3	D2	D1	D0			
Initial setup 1	01	Advanced switch ON/OFF	0	of Input Ga Tone/Fade	switch time ain/Volume er/Loudnes s	0	0	Advanced of N				
Initial setup 2	02	LPF Phase	Level Meter RESET	0	0	0	Subwoofer LPF fc	LPF Phase	Level Meter RESET			
Initial setup 3	03	0	0	0	Loudn	ess fo	0	0	1			
Input Selector	05	0	0	0 0 Input selector								
Input gain	06	Mute ON/OFF	0 0 Input Gain									
Volume gain	20			\	olume Gain	/ Attenuation	n					
Fader 1ch Front	28		Fader Gain / Attenuation									
Fader 2ch Front	29		Fader Gain / Attenuation									
Fader 1ch Rear	2A		Fader Gain / Attenuation									
Fader 2ch Rear	2B				Fader Gain	/ Attenuation	n					
Fader Subwoofer	2C				Fader Gain	/ Attenuation	n					
Bass setup	41	0	0	Bas	s fo	0	0	Bas	s Q			
Middle setup	44	0	0	Midd	lle fo	0	0	Midd	lle Q			
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q			
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain					
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain							
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain							
Loudness Gain	75	0	Loudne	ss HiCut		L	oudness Ga	in				
System Reset	FE	1	0	0	0	0	0	0	1			

Advanced switch

Note

- 1. The advance switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls back to the first address on automatic increment function, as shown below.

$$01 \rightarrow 02 \rightarrow 03 \rightarrow 05 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C$$

$$\rightarrow 41 \rightarrow 44 \rightarrow 47 \rightarrow 51 \rightarrow 54 \rightarrow 57 \rightarrow 75$$

- Advanced switch is not used for the function of input selector. Therefore, please turn on MUTE when changing the settings of this side of a set.
- When using Mute function when changing input selector, please switch Mute ON/OFF for waiting advanced-mute time.

Select address 01 (hex)

	OK)									
Timo	MSB	SB Advanced switch time of Mute								
Time	D7	D6	D5	D4	D3	D2	D1	D0		
0.6msec	Advanced		Advonced	awitah tima			0	0		
1.0msec	Advanced Switch	0		switch time		_	0	1		
1.4msec	ON/OFF	U		ain/Volume er/Loudness	0	0	1	0		
3.2msec	ON/OFF		Tone/rade	er/Loudness			1	1		

Time	MSB	Advanced switch time of Input gain/Volume/Tone/Fader/Loudness								
	D7	D6	D5	D4	D3	D2	D1	D0		
4.7 msec	A alvers a a al	0	0	0	0	0	Advanced switch			
7.1 msec	Advanced		0	1						
11.2 msec	Switch ON/OFF		1	0			Time	of Mute		
14.4 msec			1	1						

Mode	MSB	SB Advanced switch ON/OFF							
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	Advanced switch time of Input gain/Volume Tone/Fader/Loudness		0	0	Advanced switch		
ON	1	O			O	O	Time o	of Mute	

Select address 02(hex)

40	MSB	MSB Subwoofer LPF fc							
tc	D7	D6	D5	D4	D3	D2	D1	D0	
OFF						0	0	0	
55Hz		Level Meter RESET	0	0		0	0	1	
85Hz	LPF Phase				0	0	1	0	
120Hz	LFFFIIdSe				U	0	1	1	
160Hz						1	0	0	
Prohibition						Other setting			

Mode	MSB		Lev	Level Meter RESET					
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
HOLD	LDE Dhoos	0	0	0	0	c.	bwoofer LPF	- 40	
RESET	LPF Phase	1	U	U	U	Su	bwooiei LPi	- 10	

Phase	MSB				LSB			
Filase	D7	D6	D5	D4	D3	D2	D1	D0
0°	0	Level Meter	0	0	0	Q.I.	= fc	
180°	1	RESET	U	U	U	Su	bwoofer LPF	ic

Select address 03(hex)

fO	MSB				LSB			
10	D7	D6	D5	D4	D3	D2	D1	D0
250Hz				0	0			
400Hz	_			0	1	0	0	4
800Hz	U	0	0	1	0	U	U	l I
Prohibition				1	1			

Select address 05(hex)

Mode	OUT	OUT	MSB		I	nput S	electo	r		LSB
Mode	F1/R1	F2/R2	D7	D6	D5	D4	D3	D2	D1	D0
	Initial						0	0	0	0
Α	A1	A2					0	0	0	1
В	B1	B2					0	0	1	0
C diff	CP1	CP2	0	0	0	0	0	1	1	0
D	D1	D2	U	U	U	U	1	0	1	0
Е	E1	E2					1	0	1	1
Inp	out SHC	RT					1	0	0	1
Prohibition					Other setting					

Input SHORT : The input impedance of each input terminal is lowered from 100kΩ(Typ) to 6 kΩ(Typ). (For quick charge of coupling capacitor)

Select address 06 (hex)

Gain	MSB			Input	Gain			LSB
Gairi	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Mute			0	1	0	1	1
12dB	ON/OFF	0	0	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	1	0	1	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

Mode	MSB			Mute 0	LSB			
iviode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	0			Input Gain		
ON	1		0			Input Gain		

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	ol, Fad	er Gai	n / Atte	enuatio	on	LSB
Gaill & All I	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	÷	•	÷	:	:	•	÷	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 41(hex)

OCICOL addices + I (IICX	,							
Q factor	MSB		E	Bass	Q fact	or		LSB
Q Iacioi	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0		0	Por	ss fo		_	0	1
1.5			Das	55 10			1	0
2.0							1	1

fo	MSB			Bass	s fo			LSB
fo	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz	0	^	0	1	0	0	Ba	ass actor
100Hz	U	U	1	0	U	U	Q fa	actor
120Hz			1	1				

Select address 44(hex)

Q factor	MSB		M	iddle	Q fac	tor		LSB
Qiacioi	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	0	0	Mida	dle fo	0	0	0	1
1.25	U	U	iviido	ile io	0	U	1	0
1.5							1	1

fo	MSB			Midd	le fo			LSB
TO	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	0	0	0	1	0	0	Mic	ddle
1.5kHz	U	U	1	0	U	U	Q fa	actor
2.5kHz			1	1				

Select address 47 (hex)

Q factor	MSB	·	Tı	reble	Q fact	Q factor		
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Trok	ole fo	0	0	0	0
1.25] 0	0	lier	DIE 10	0	U	0	1

fo	MSB			Trebl	e fo			LSB
10	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz			0	0				
10kHz]	_	0	1		0		Treble
12.5kHz] 0	0	1	0] 0	U	0	Q factor
15kHz			1	1				

Select address 51, 54, 57 (hex)

Gain	MSB								
Gairi	D7	D6	D5	D4	D3	D2	D1	D0	
0dB				0	0	0	0	0	
1dB				0	0	0	0	1	
2dB				0	0	0	1	0	
3dB				0	0	0	1	1	
4dB				0	0	1	0	0	
5dB				0	0	1	0	1	
6dB				0	0	1	1	0	
7dB				0	0	1	1	1	
8dB				0	1	0	0	0	
9dB				0	1	0	0	1	
10dB	Bass/			0	1	0	1	0	
11dB	Middle/			0	1	0	1	1	
12dB	Treble	0	0	0	1	1	0	0	
13dB	Boost	· ·		0	1	1	0	1	
14dB	/Cut			0	1	1	1	0	
15dB				0	1	1	1	1	
16dB				1	0	0	0	0	
17dB				1	0	0	0	1	
18dB				1	0	0	1	0	
19dB				1	0	0	1	1	
20dB				1	0	1	0	0	
				1	0	1	0	1	
Prohibition				:	:	:	:	:	
1 TOTALOTT				1	1	1	1	0	
				1	1	1	1	1	

Mode	MSB	Ba	ss/ Mi	ddle/ T	reble l	Boost/	Cut	LSB	
Mode	D7	D6	D5	D4	D3	D2	D1	D0	
Boost	0	0	0		Poss/I	Middle/Troble	o Coin		
Cut	1	O	U	Bass/Middle/Treble Gain					

: Initial condition

Select address 75 (hex)

00:001 000:000 10 (1:0)	,/							
Mode	MSB		L	oudne	ss HiC	ut		LSB
iviode	D7	D6	D5	D4	D3	D2	D1	D0
HiCut1		0	0					
HiCut2		0	1			oudness Gai	n	
HiCut3		1	0		L	oudriess Gai	[]	
HiCut4		1	1					

Gain	MSB		L	oudne	ss Gai	in		LSB
Gaill	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	_			0	1	0	1	1
12dB	0	Loudne	ss HiCut	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
				1	1	1	1	1

: Initial condition

(6) About Power ON Reset
The IC has a built-in initialization circuit that triggers at power ON of supply voltage. Please send initial data to all addresses at supply voltage ON. Also, please turn ON MUTE at the set side until this initial data is sent.

Parameter	Symbol		Limit		Unit	Conditions
Farameter	Symbol	Min	Тур	Max	Offic	Conditions
Rise Time of VCC	t _{RISE}	33	-	-	µsec	V _{CC} rise time from 0V to 5V
VCC Voltage of Release Power ON Reset	V _{POR}	-	4.1	-	V	

(7) About External Compulsory Mute Terminal

It is possible to forcibly set Mute externally by setting the input voltage at the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

Application Information

1. Function and Specifications

Function	Specifications
Input selector	· Stereo 4 input · Differential 1 input
Innut goin	· +20dB to 0dB (1dB step)
Input gain	· Possible to use "Advanced switch" for prevention of switching noise.
Mute	Possible to use "Advanced switch" for prevention of switching noise.
Volume	· +15dB to -79dB (1dB step), -∞dB
volume	· Possible to use "Advanced switch" for prevention of switching noise.
	· +20dB to -20dB (1dB step) · Q=0.5, 1, 1.5, 2 variable
Bass	· fo=60, 80, 100, 120Hz
	· Possible to use "Advanced switch" at changing gain
	· +20dB to -20dB (1dB step) · Q=0.75, 1, 1.25, 1.5 variable
Middle	· fo=500, 1k, 1.5k, 2.5kHz variable
	· Possible to use "Advanced switch" when changing gain
	· +20dB to -20dB (1dB step) · Q=0.75, 1.25 variable
Treble	· fo=7.5k, 10k, 12.5k, 15kHz variable
	Possible to use "Advanced switch" when changing gain
Fader	· +15dB to -79dB(1dB step), -∞dB
i auei	· Possible to use "Advanced switch" for prevention of switching noise.
Loudness	· 20dB to 0dB(1dB step) · fo=250/400/800Hz
Loudiless	· Possible to use "Advanced switch" for prevention of switching noise.
LPF	· fc=55/85/120/160Hz, pass · Phase shift (0°/180°)
Level meter	· I ² C BUS control · DC Output

2. Volume / Fader Volume Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3 -4	1	0	0	0	0	0 1	0	0	-51 -52	1	0	1	1	0	0 1	0	0
- 4 -5	1	0	0	0	0	1	0	1	-52 -53	1	0	1	1	0	1	0	1
-5 -6	1	0	0	0	0	1	1	0	-53 -54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-5 4 -55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25 26	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	0
-26 -27	1	0	0	1	1	0	1	0	-74 -75	1	1	0	0	1	0	1	1
-27	1	0	0	1	1	1	0	0	-75 -76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-76 -77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-77 -78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-00	1	1	1	1	1	1	1	1
J2				J	J	J											'

(1) About Level Meter

(a) The Operation of Circuit

Level meter is a function which gives DC voltage proportional to the size of signal of sound. It detects the peak level of signal and keeps the peak level, so that it is possible to monitor the size of signal by resetting DC voltage kept with suitable interval.

(b) The Way to Reset Level Meter Output

Please send reset data through I²C BUS

To reset output of level meter: Send D6 = "1" of select address 02(hex).

To cancel output reset of level meter (HOLD)... to Send D6 = "0" of select address 02(hex).

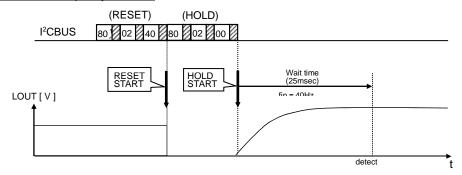
(c) The Settings About Period of Reset

Peak hold operation will start after HOLD data is transmitted. Set the WAIT time after HOLD data transmission according to the frequency bandwidth detected.

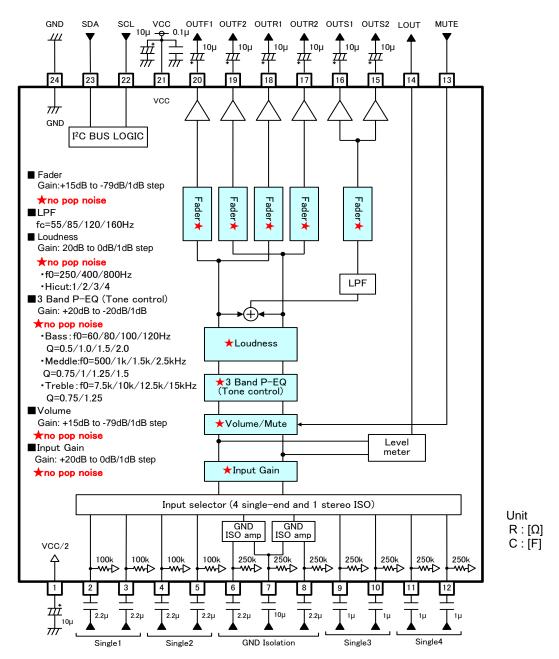
WAIT time must be set to a minimum of one cycle over the detected frequency bandwidth.

Ex) Detected frequency bandwidth is above 40Hz, \$\t^240Hz = 25ms = WAIT time_{\text{\text{\text{}}}}\$

Transmission Example by I²C BUS



3. Application Circuit



Notes on wiring

- \odot Please connect the decoupling capacitor of a power supply in the shortest distance as much as possible to GND.
- ② GND lines should be one-point connected.
- ③ Wiring pattern of Digital should be away from that of analog unit and crosstalk is not acceptable.
- (4) Lines of SCL and SDA of I²C BUS should not be parallel if possible. The lines should be shielded, if they are adjacent to each other.
- S Analog input lines should not be parallel if possible. The lines should be shielded if they are adjacent to each other.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC are greatly affected by the temperature at which it is used. Exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation..

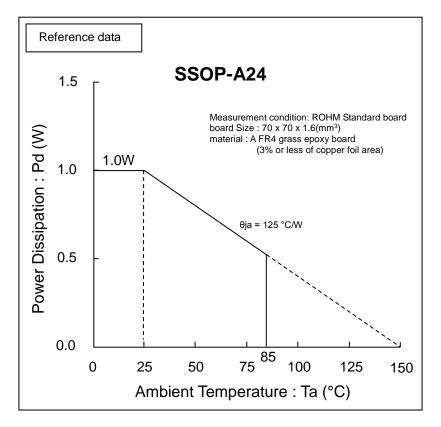


Figure 24. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Pin	Pin	Pin	Equivalent Circuit	Pin Description
No. 2 3 4 5	A1 A2 B1 B2	Voltage 4.25	VCC VO NO	A terminal for signal input. The input impedance is 100kΩ(typ).
6 7 8 9 10 11	CP1 CN CP2 D1 D2 E1	4.25	VCC A SE 250k	A terminal for signal input. The input impedance is 250kΩ(typ).
13	MUTE	-	VCC A BU BU 1.65V	A terminal for external compulsory mute. If terminal voltage is High level, the mute is OFF. If the terminal voltage is Low level, the Mute is ON.
16 17 18 19 20	OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for Fader and Subwoofer output.

The values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

I/O Equivalent Circuits - continued

Pin No.	Pin Name	Pin Voltage	Equivalent Circuit	Pin Description
21	VCC	8.5		Power supply terminal.
22	SCL	-	VCC O 1.65V	A terminal for clock input of I ² C BUS communication.
23	SDA	-	VCC O O I.65V	A terminal for data input of I ² C BUS communication.
24	GND	0		Ground terminal.
1	FIL	4.25	VCC	Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.

The values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes - continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

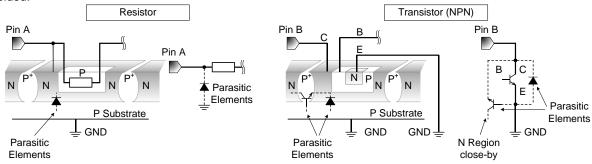
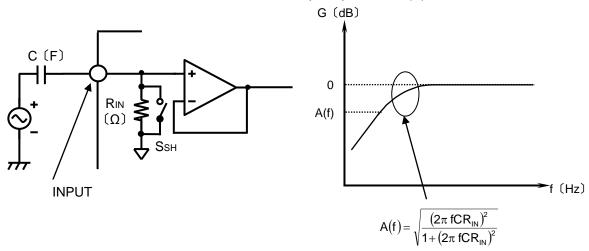


Figure 25. Example of monolithic IC structure

13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value

In the input signal terminal, please decide the constant value of the input coupling capacitor C(F) that would be sufficient to form an RC characterized HPF with input impedance $R_{IN}(\Omega)$ inside the IC.



(b) About the Input Selector SHORT

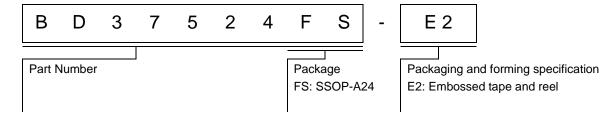
SHORT mode is the command which makes switch S_{SH} =ON of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns

14. About Mute Terminal(Pin 13) when power supply is OFF

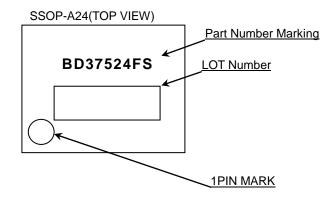
There should be no applied voltage across the Mute terminal (Pin 13) when power-supply is OFF. A resistor (about $2.2k\Omega$) should be connected in series to Mute terminal in case a voltage is supplied to Mute terminal. (Please refer Application Circuit Diagram.)

ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

Ordering Information



Marking Diagram



Physical Dimension, Tape and Reel Information Package Name SSOP-A24 Max10.35 (include. BURR) 8 ± 0 . 4 ± 0 . 2 ± 0 . H 0 $0.\ \ 1\ 7\ ^{+0.\ 1}_{-0.\ 0\ 5}$ 8 ± 0 . (UNIT: mm) $0.1\pm 0.$ PKG:SSOP-A24 Drawing No. : EX133-5001-1 0. 38 ± 0.1 0.8 □ 0. 1 <Tape and Reel information> Embossed carrier tape Tape Quantity 2000pcs **E2** Direction The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand of feed Direction of feed 1pin Reel *Order quantity needs to be multiple of the minimum quantity.

Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSIIb	CI VCCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [h] Use of the Products in places subject to dew condensation
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 - [d] the Products are exposed to high Electrostatic
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